

## WaveEtch™ wet processing performance

Matech™'s new WaveEtch™ system introduces the most advanced wet processing technology. The WaveEtch™ offers unparalleled etching uniformity on thin films in a fully automated cassette-to-cassette tool. Our latest data show that the WaveEtch™ system is the ideal tool for thinning nitride films, as it achieves process uniformities under 1%. During the removal of 800A of plasma nitride, the WaveEtch™ yields a film thickness standard deviation of 0.7% ! This performance offers cost, quality, and yield benefits in the production of your latest devices. In addition, it allows for the introduction of advanced process steps due to its true single-sided capabilities.

Analysis of our latest processed wafers show typical nitride film thickness standard deviations of less than 1% ! Figure 1 shows a surface topographic map that illustrates the high degree of uniformity that can be achieved while thinning nitride films with a WaveEtch™ system. See table to the right for a summary of system performance.

Contact Matech™ now to increase your wet processing quality and productivity!

## MATECH's breakthrough system excels in single sided wet processing!

### Thickness of Silicon Nitride Film on 75mm Wafer

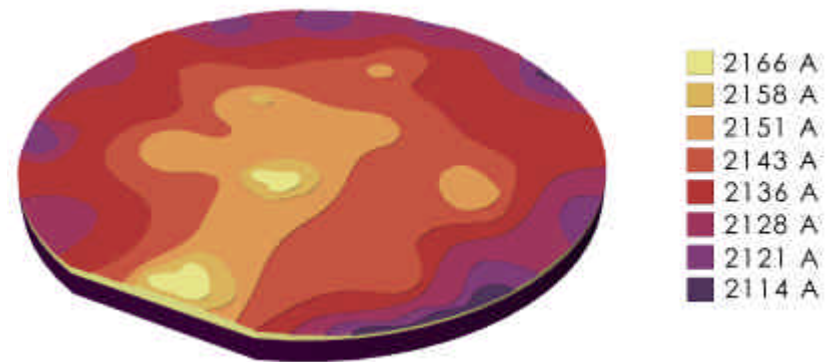


Figure 1

### Nitride Film Statistical Analysis

|       |      |           |
|-------|------|-----------|
| MEAN  | 2141 | Angstroms |
| STDEV | 16   | Angstroms |
| MAX   | 2168 | Angstroms |
| MIN   | 2114 | Angstroms |
| RANGE | 54   | Angstroms |

